

### General Description

The MA2605V is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the small power switching and load switch applications.

The MA2605V meet the RoHS and Green Product requirement with full function reliability approved.

### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent C<sub>dv/dt</sub> effect decline
- Green Device Available

### Absolute Maximum Ratings

Symbol	Parameter	Rating				Units
		N-Channel		P-Channel		
		10s	Steady State	10s	Steady State	
V <sub>DS</sub>	Drain-Source Voltage	20		-20		V
V <sub>GS</sub>	Gate-Source Voltage	± 8		± 8		V
I <sub>D@T<sub>A</sub>=25</sub>	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	4.3	3.8	-2.9	-2.5	A
I <sub>D@T<sub>A</sub>=70</sub>	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	3.4	3	-2.3	-2	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	15.2		-10		A
P <sub>D@T<sub>A</sub>=25</sub>	Total Power Dissipation <sup>3</sup>	1.5	1.1	1.5	1.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		-55 to 150		
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150		-55 to 150		

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	110	/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	85	/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	70	/W

Rev A.03 D052711

### Product Summary

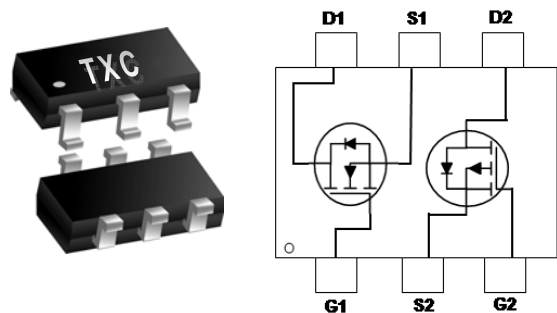


BVDSS	R <sub>DS(on)</sub>	ID
20V	48mΩ	3.8A
-20V	130mΩ	-2.5A

### Applications

- High Frequency Point-of-Load Synchronous s
- Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### TSOP6 Pin Configuration



### N-Channel Electrical Characteristics ( $T_J=25$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$BV_{DSS}/T_J$	BVDSS Temperature Coefficient	Reference to 25 , $I_D=1mA$	---	0.024	---	V/
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=4.5V, I_D=3A$	---	40	48	m $\Omega$
		$V_{GS}=2.5V, I_D=2A$	---	45	55	
		$V_{GS}=1.8V, I_D=1.5A$	---	55	65	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.5	1	V
$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2.51	---	mV/
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V, T_J=25$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=55$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=3A$	---	9	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.7	3.4	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=4.5V, I_D=3A$	---	6.2	8.7	nC
$Q_{gs}$	Gate-Source Charge		---	0.36	0.5	
$Q_{gd}$	Gate-Drain Charge		---	1.56	2.18	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=10V, V_{GS}=4.5V, R_G=3.3\Omega, I_D=3A$	---	1.4	2.8	ns
$T_r$	Rise Time		---	40	72.0	
$T_{d(off)}$	Turn-Off Delay Time		---	17	34	
$T_f$	Fall Time		---	5.6	11.2	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	382	534.8	$\mu F$
$C_{oss}$	Output Capacitance		---	41	57.4	
$C_{rss}$	Reverse Transfer Capacitance		---	33	46.2	

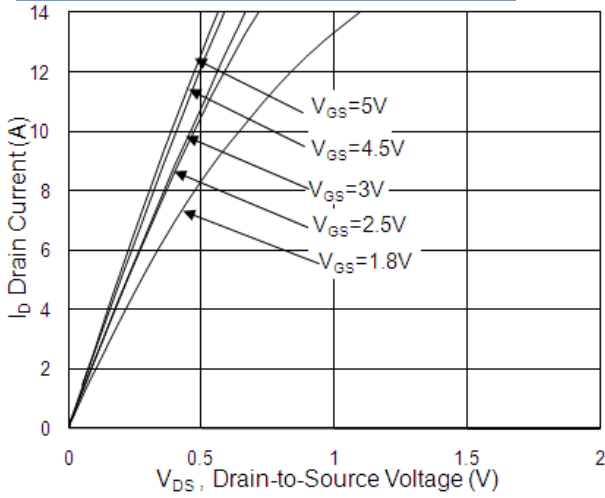
### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V, \text{Force Current}$	---	---	3.8	A
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	15.2	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=3A, di/dt=100A/\mu s, T_J=25$	---	5.7	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	1.8	---	nC

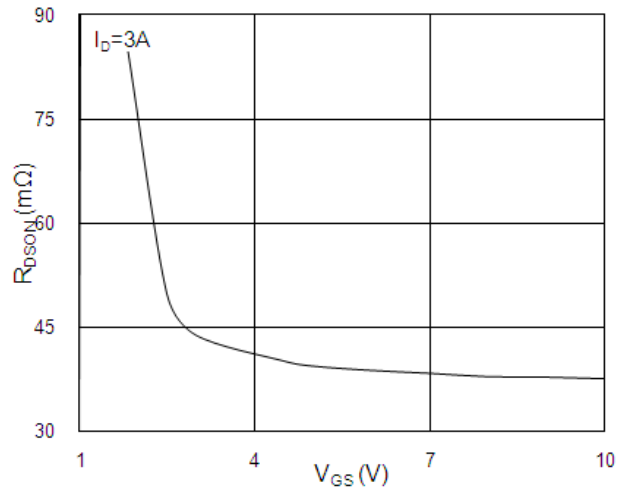
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by 150 junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

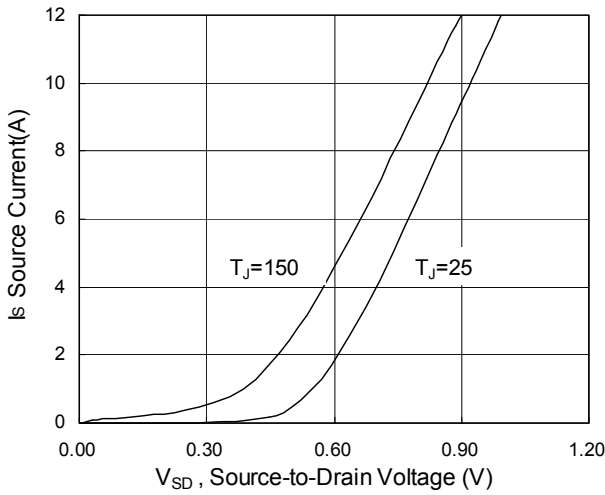
**N-Channel Typical Characteristics**



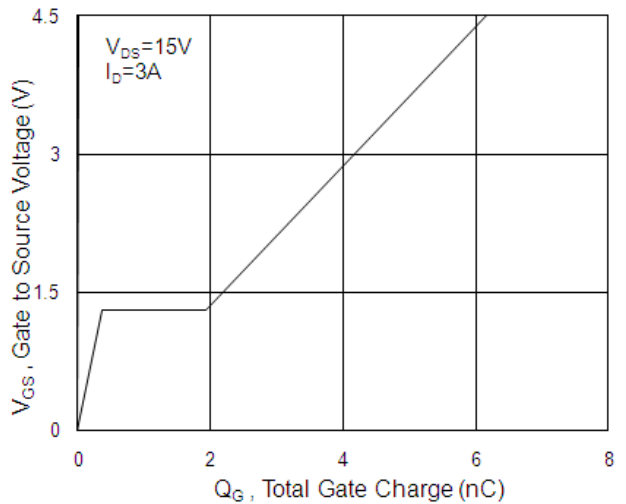
**Fig.1 Typical Output Characteristics**



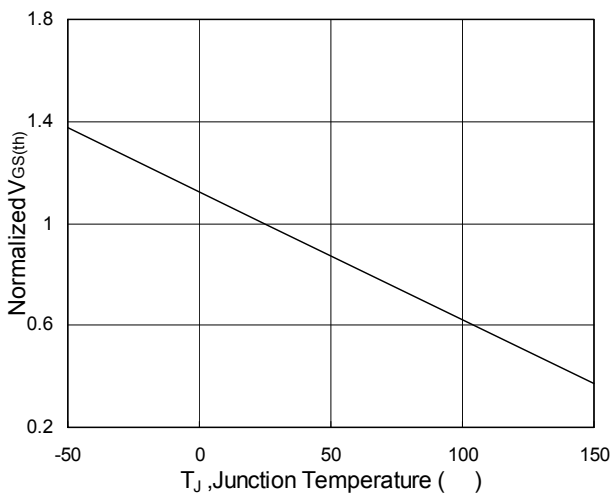
**Fig.2 On-Resistance vs. Gate-Source**



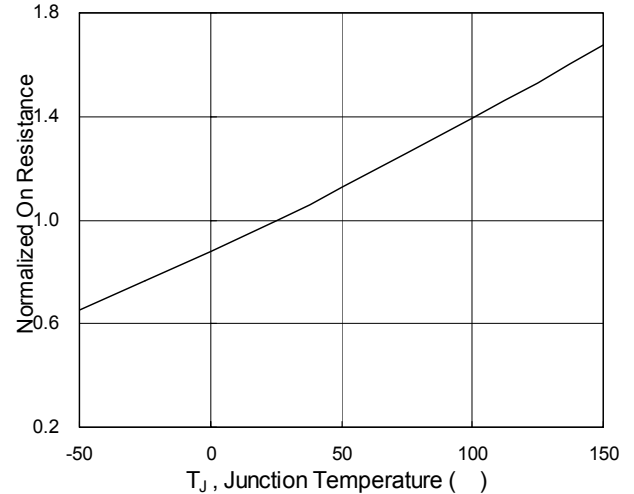
**Fig.3 Forward Characteristics Of Reverse**



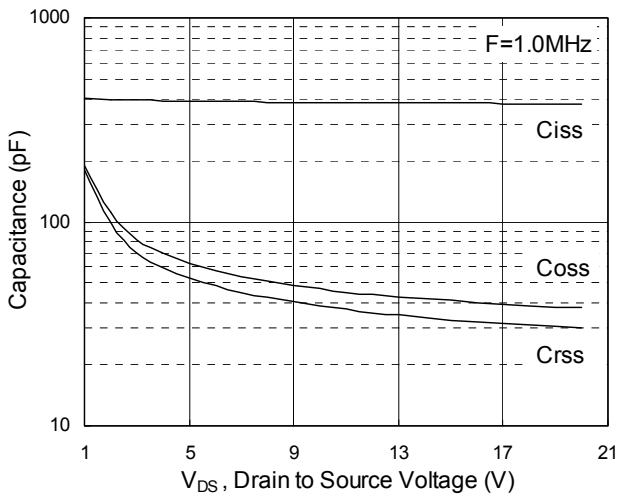
**Fig.4 Gate-Charge Characteristics**



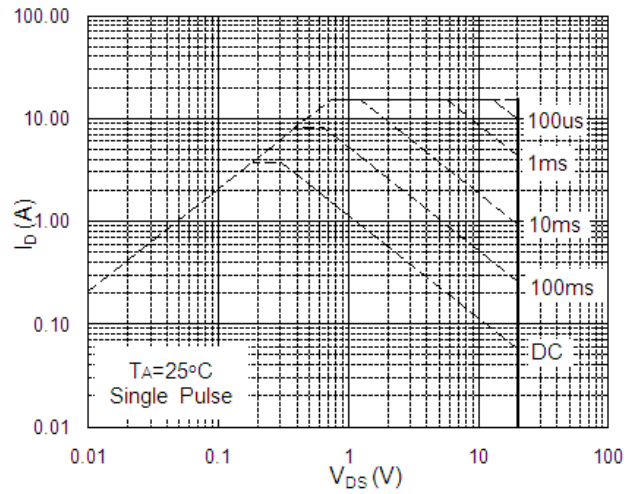
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



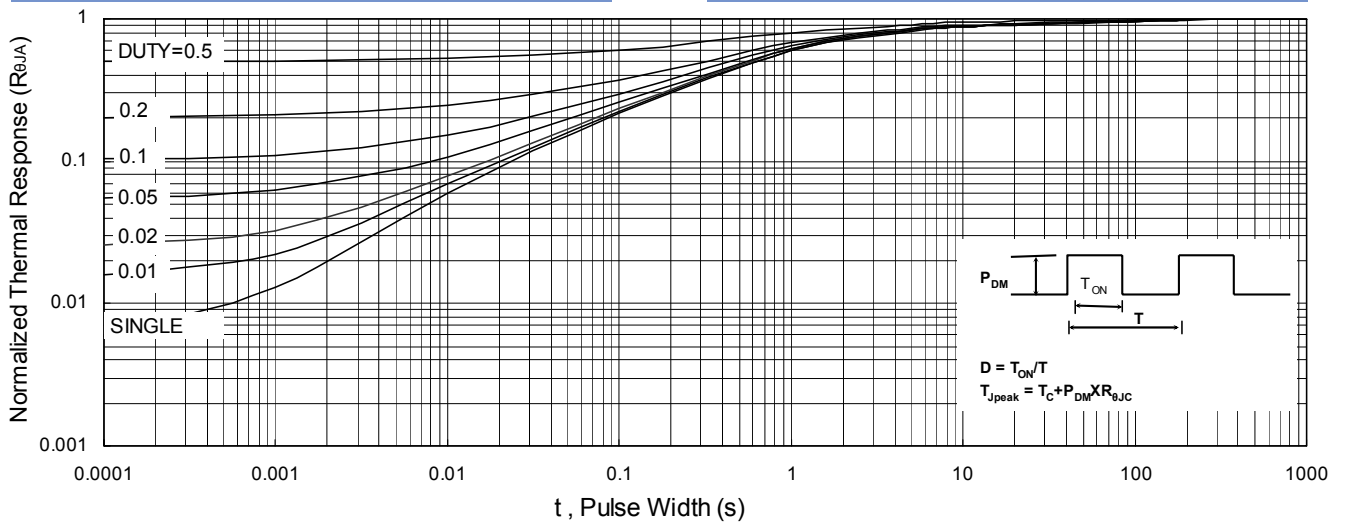
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



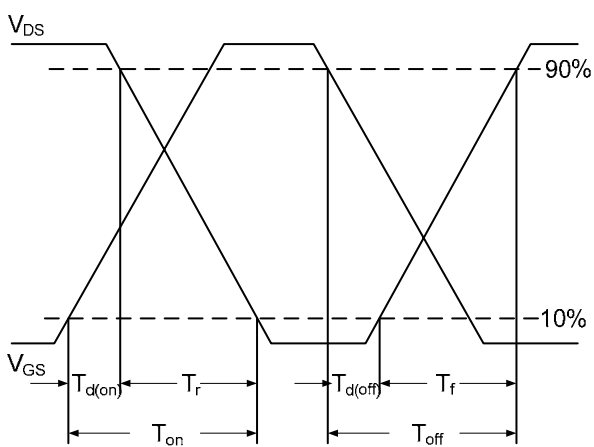
**Fig.7 Capacitance**



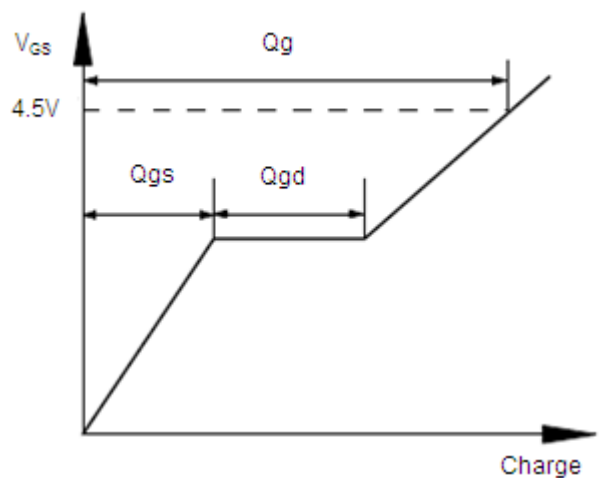
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
$BV_{DSS}/T_J$	BVDSS Temperature Coefficient	Reference to 25 , $I_D=-1mA$	---	-0.016	---	V/
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-4.5V, I_D=-2.5A$	---	105	130	m $\Omega$
		$V_{GS}=-2.5V, I_D=-1.5A$	---	145	170	
		$V_{GS}=-1.8V, I_D=-1A$	---	185	220	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.5	-1	V
$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3.97	---	mV/
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-16V, V_{GS}=0V, T_J=25$	---	---	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V, T_J=55$	---	---	-5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5V, I_D=-2A$	---	5.9	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	13.1	26.2	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-2A$	---	5.6	7.8	nC
$Q_{gs}$	Gate-Source Charge		---	0.72	1.0	
$Q_{gd}$	Gate-Drain Charge		---	1.45	2.0	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-4.5V, R_G=3.3\Omega, I_D=-2A$	---	4	8.0	ns
$T_r$	Rise Time		---	25.6	46	
$T_{d(off)}$	Turn-Off Delay Time		---	26	52	
$T_f$	Fall Time		---	12.4	24.8	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	332	465	$\mu F$
$C_{oss}$	Output Capacitance		---	48	67	
$C_{riss}$	Reverse Transfer Capacitance		---	42	59	

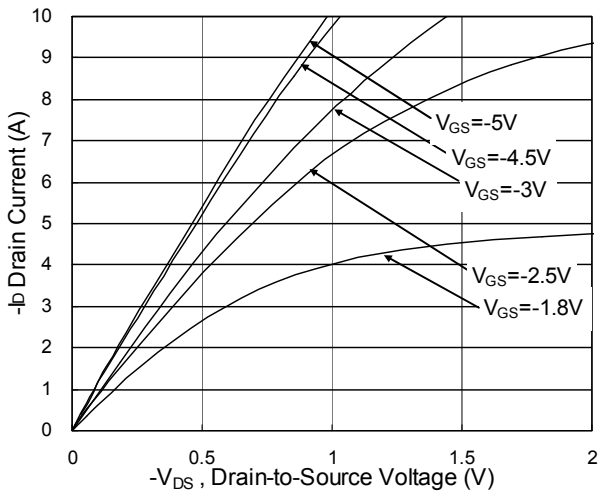
### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V, \text{Force Current}$	---	---	-2.5	A
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	-10	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25$	---	---	-1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=-2A, dI/dt=100A/\mu s, T_J=25$	---	23	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	4.7	---	nC

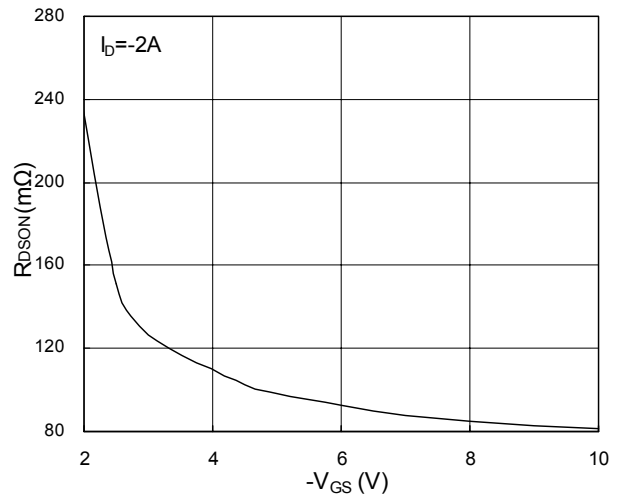
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by 150 junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

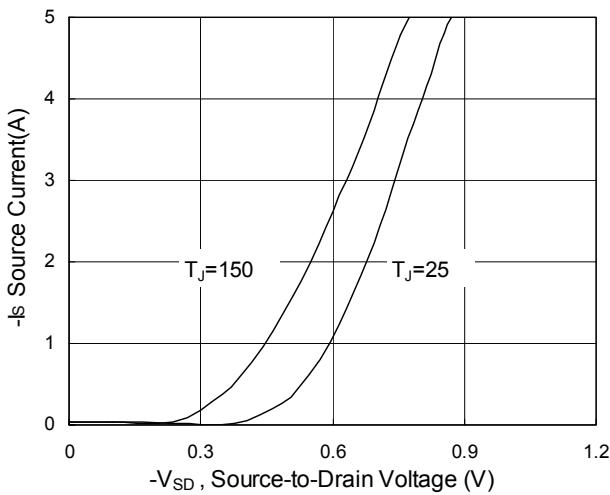
### P-Channel Typical Characteristics



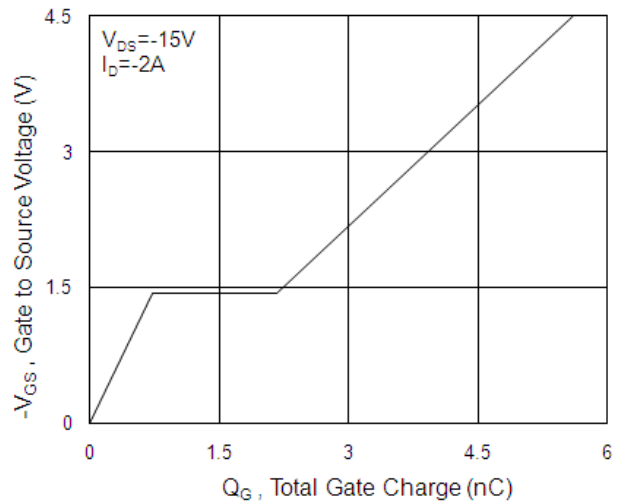
**Fig.1 Typical Output Characteristics**



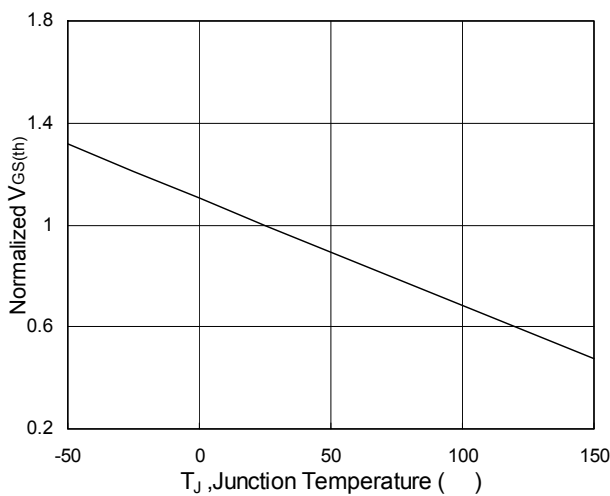
**Fig.2 On-Resistance vs. Gate-Source**



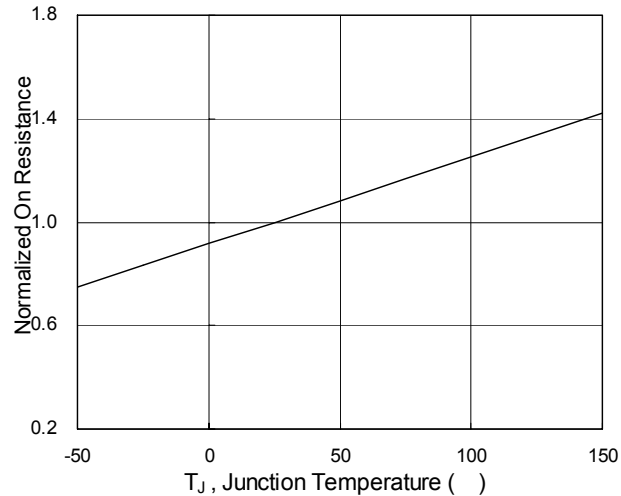
**Fig.3 Forward Characteristics Of Reverse**



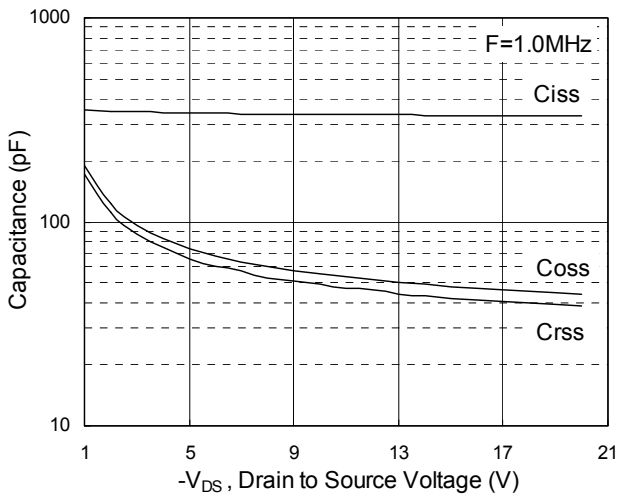
**Fig.4 Gate-Charge Characteristics**



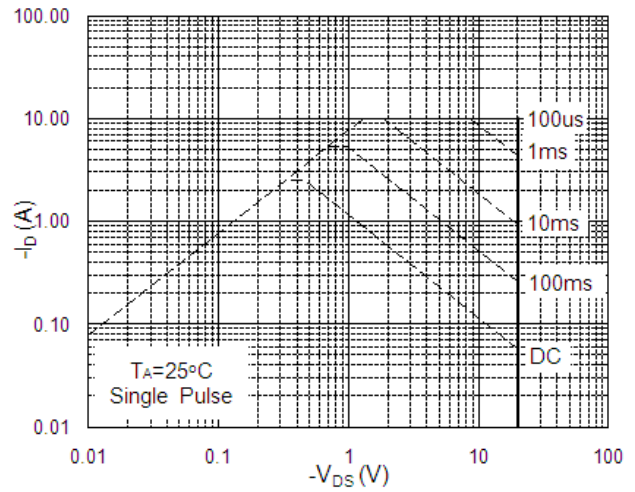
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



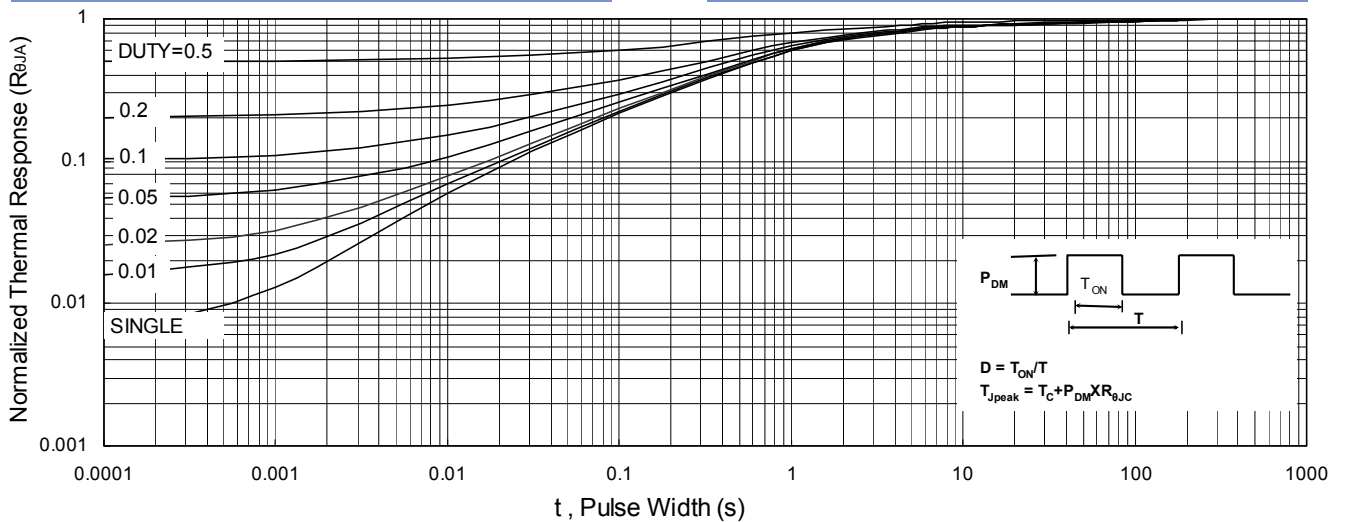
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



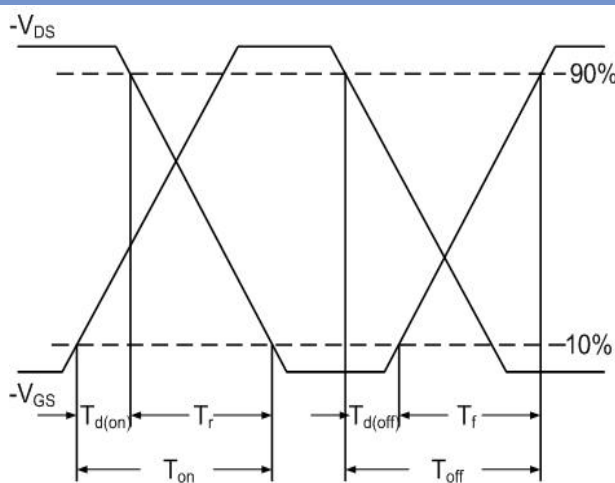
**Fig.7 Capacitance**



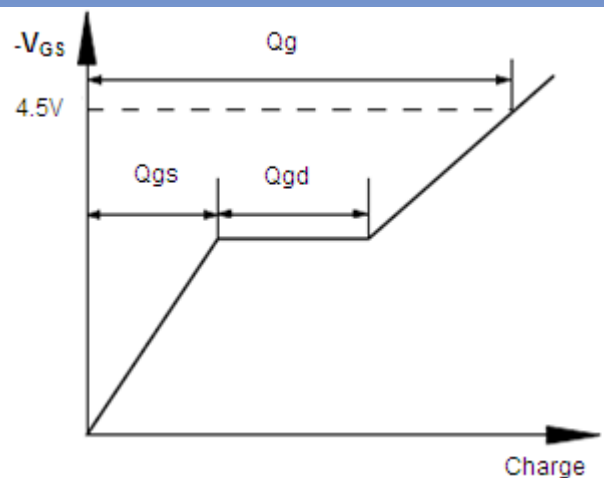
**Fig.8 Safe Operating Area**



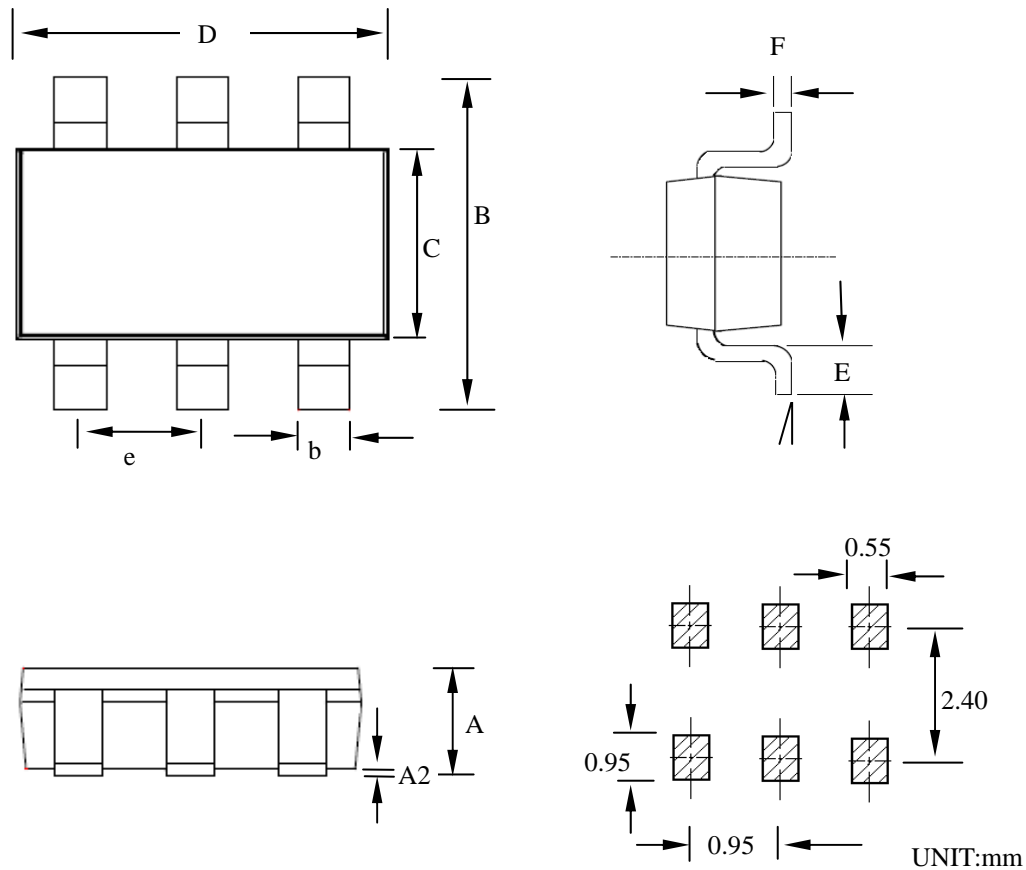
**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**

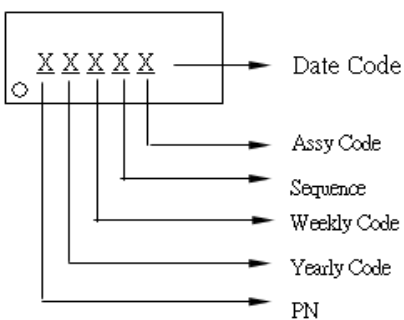


**Fig.11 Gate Charge Waveform**



LAND PATTERN RECOMMENDATION

### MARKING



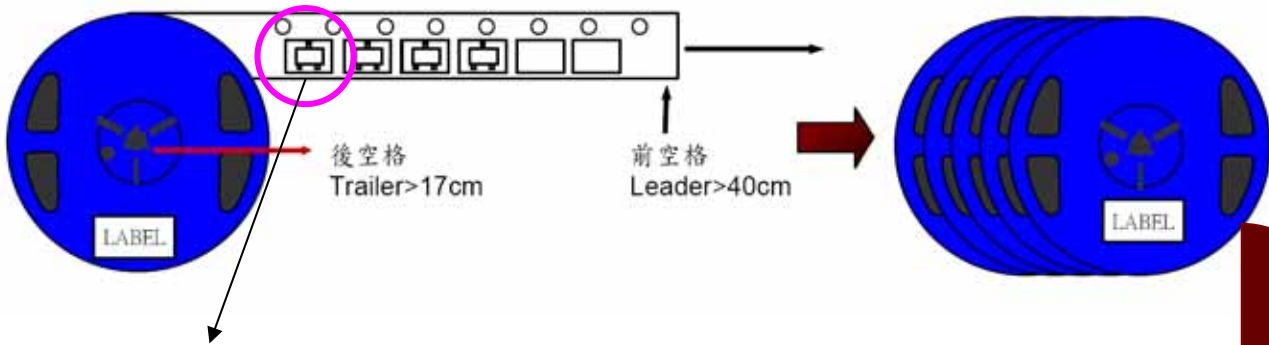
SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
A2	0.00	--	0.10	0.000	--	0.004
B	2.60	2.80	3.00	0.102	0.110	0.118
C	1.40	1.60	1.80	0.055	0.063	0.071
D	2.70	2.90	3.10	0.106	0.114	0.122
E	0.30	0.40	0.60	0.012	0.016	0.024
F	0.07	0.127	0.20	0.003	0.005	0.008
b	0.30	0.40	0.50	0.012	0.016	0.020
e	--	0.95	--	--	0.037	--
θ	0°	5°	10°	0°	5°	10°

**Note:**

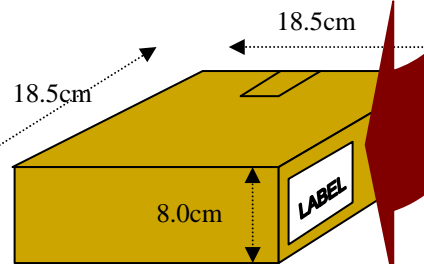
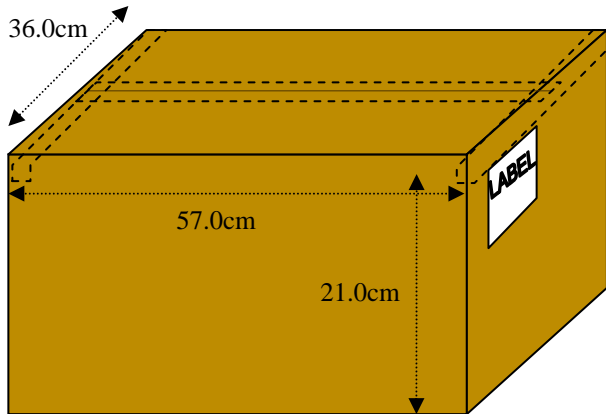
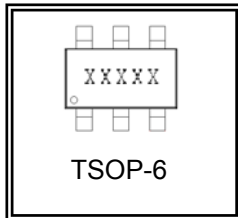
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. CONTROLLING DIMENSION IS MILLIMETER CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACTLY.



Tape & Reel 繞捲及裝箱方式 - TSOP-6



產品正印及方向 - (正印為正時, Tape 圓孔在上方)



封裝形態 PKG TYPE	一般包裝		
	一卷數量 Immediate Quantity	中箱數量 Intermediate Quantity	外箱裝置/數量 Carton Quantity
TSOP-6	3000pcs	15000pcs	180 K
	Reel ( 7" )	Box(5 reels)	Carton(12 Box)